

ABSTRACT OF THE DISCLOSURE

A method for making a through-hole in a silicon substrate includes the steps of forming a high-impurity-concentration region in the periphery of a through-hole-forming region at a first surface of the silicon substrate, forming an etching stop layer over the through-hole-forming region and the high-impurity-concentration region, forming a mask layer having an opening at a second surface of the silicon substrate, etching the silicon substrate at the opening through the mask layer until the etching stop layer is exposed to the second surface, further etching the silicon substrate until the etched portion extends to the high-impurity-concentration region, and removing the etching stop layer at least at the portion exposed to the second surface. Also disclosed is an ink-jet printer head including an ink supply port fabricated using the method for making the through-hole.